

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An optical module comprising:
an optical subassembly including a semiconductor optical device;
a housing including a base and a cover, the base having a bottom surface ~~thereof~~, and the optical subassembly being provided between the base and the cover;
a support being in contact with the optical subassembly, the support being disposed on the bottom surface of the base; and
a thermal sheet provided between the cover and the support,
wherein the support reduces a stress applied to the optical subassembly from the thermal sheet and provides a thermal path from the optical subassembly.

2. (Original) The optical module according to claim 1, wherein the support includes a first leg portion, a second leg portion and a bridge connecting the first and second leg portions with each other, the cover and the bridge sandwiching the thermal sheet therebetween, and the optical subassembly is provided between the first and second leg portions.

3. (Currently Amended) The optical module according to claim 2, wherein the ~~first~~ first and second leg portions are in contact with the optical subassembly with solders provided between the optical subassembly and the first and second leg portions, respectively.

4. (Currently Amended) The optical module according to claim 1, wherein the optical subassembly ~~includes~~ has an outer surface and includes a stem for mounting the semiconductor optical device, and

wherein the support includes a first leg portion, a second leg portion, a bridge connecting the first and second leg portions with each other, and a finger curved so as to be in contact with the outer surface of the stem, the first and second leg portions providing the optical subassembly therebetween, and the thermal sheet being provided between the bridge and the cover.

5. (Original) The optical module according to claim 4, wherein the outer surface of the optical subassembly is spaced from the bridge.

6. (Original) The optical module according to claim 4, wherein the finger is in contact with the stem with a solder provided between the stem and the finger.

7. (Withdrawn) The optical module according to claim 4, wherein the support has another bridge for securing the finger with the first and second leg portions.

8. (Withdrawn) The optical module according to claim 7, wherein a level of the bridge relative to the bottom surface of the base is greater than a level of the other bridge relative to the bottom surface of the base.

9. (Withdrawn) The optical module according to claim 7, wherein the other bridge is spaced from the outer surface of the stem.

10. (Withdrawn) The optical module according to claim 7, wherein the support further includes first and second arms provided on sides of the first and second leg portions for

connecting the other bridge to the first and second leg portions, the first and second arms being connected with each other by the other bridge.

11. (Withdrawn) The optical module according to claim 10, wherein the other bridge has an inner side facing to the bridge, the finger being provided on the inner side.

12. (Withdrawn) The optical module according to claim 11, further comprising a circuit board provided in the housing,

wherein the optical subassembly has a lead terminal, connected to the circuit board.